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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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HSMB-C1xx

Surface Mount ChipLEDs



Data Sheet

HSMB-C112, HSMB-C172, HSMB-C192,
HSMB-C196, HSMB-C152



Description

This series of low current blue ChipLEDs is designed specifically for low current application. This makes them very suitable for cellular phone and portable equipment which runs off a battery. These parts are according to industry standard footprint. In order to facilitate automated pick and place operation, these ChipLEDs are shipped in tape and reel, with 4000 units per reel for HSMB-C172/192/196 series and 3000 units per reel for the HSMB-C112/152 series. These parts are compatible with IR soldering.

Features

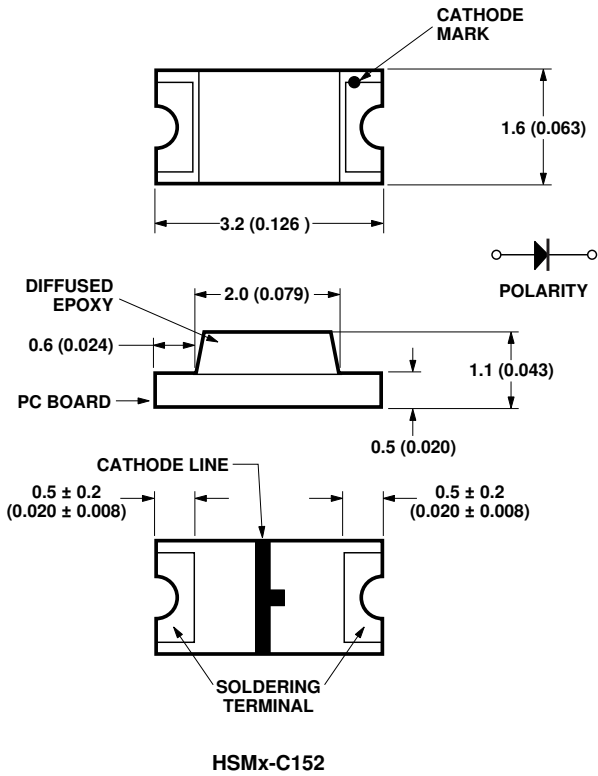
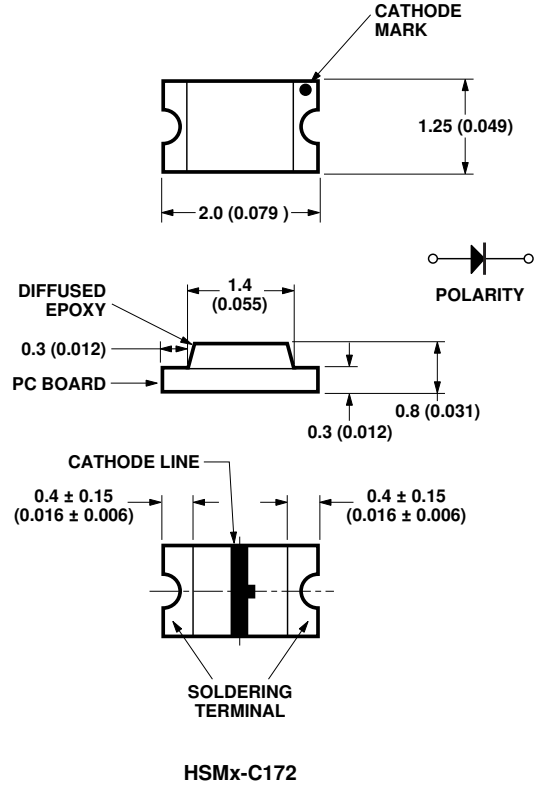
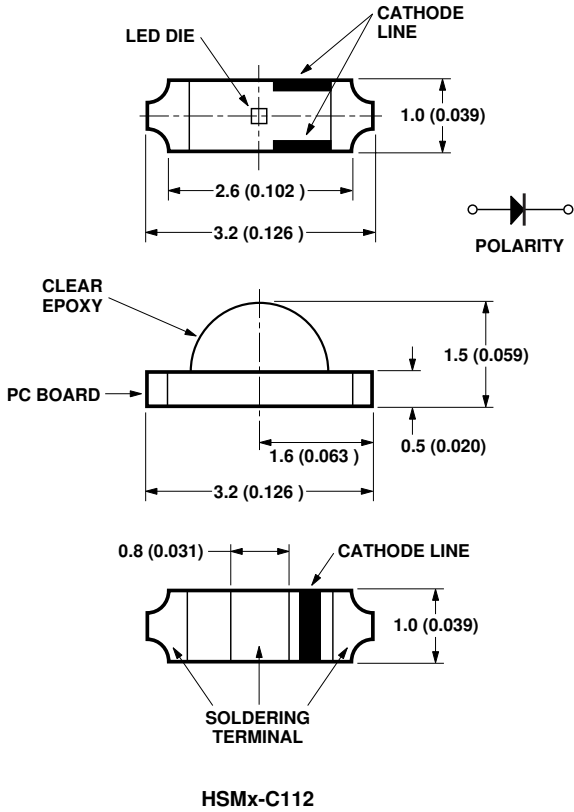
- Various size and mount options available
- Industry standard footprint
- Operating temperature range of -30°C to $+85^{\circ}\text{C}$
- Compatible with IR solder reflow
- Available in 8 mm tape on 7" diameter reel

Applications

- LCD backlighting
- Keypad backlighting
- Pushbutton backlighting
- Symbol indicator
- Front panel indicator

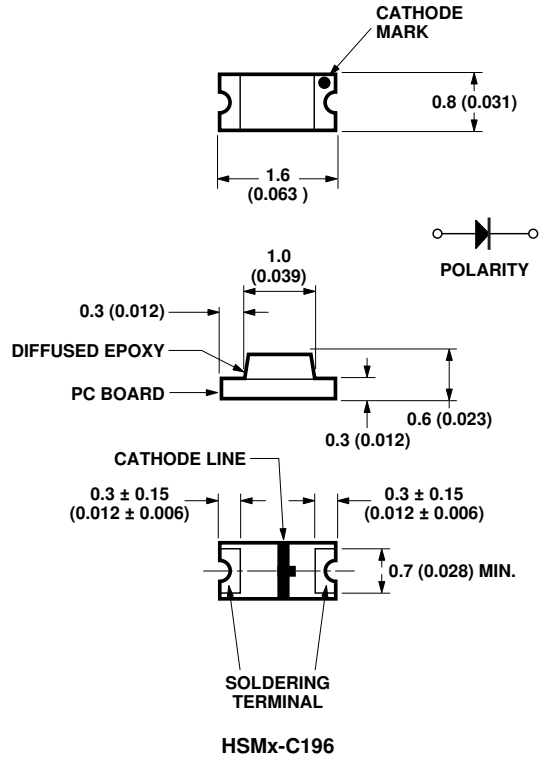
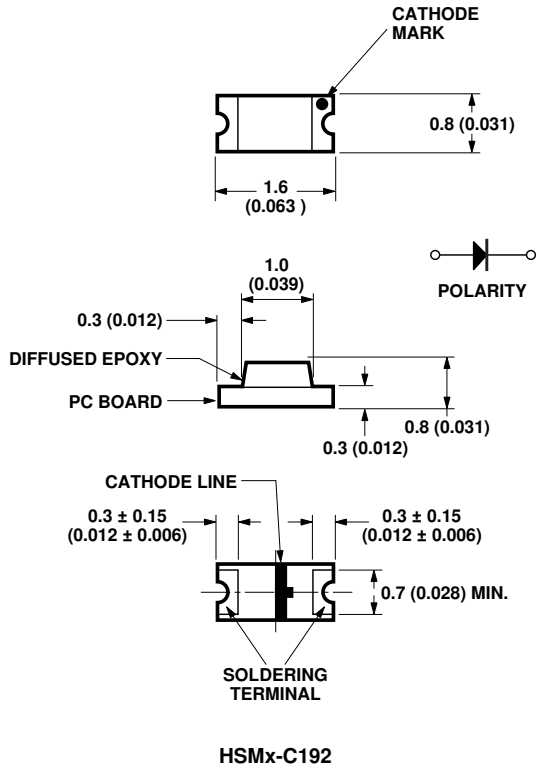
CAUTION: HSMB-C1xx LEDs are Class 1A ESD sensitive per JESD22-A114C.01. Please observe appropriate precautions during handling and processing. Refer to Avago Technologies Application Note AN-1142 for additional details.

Package Dimensions



- NOTES:**
 1. ALL DIMENSIONS IN MILLIMETERS (INCHES).
 2. TOLERANCE IS ± 0.1 mm (± 0.004 IN.) UNLESS OTHERWISE SPECIFIED.

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Device Selection Guide

Package Dimension (mm)	GaN Blue	Package Description
1.6 (L) x 0.8 (W) x 0.6 (H)	H SMB-C196	Untinted, Diffused
1.6 (L) x 0.8 (W) x 0.8 (H)	H SMB-C192	Untinted, Diffused
2.0 (L) x 1.25 (W) x 0.8 (H)	H SMB-C172	Untinted, Diffused
3.2 (L) x 1.5 (W) x 1.0 (H) ^[1]	H SMB-C112	Untinted, Nondiffused
3.2 (L) x 1.6 (W) x 1.1 (H)	H SMB-C152	Untinted, Diffused

Note:

1. Right angle package.

Absolute Maximum Ratings at T_A = 25°C

Parameter	H SMB-C112/ 172/ 192/ 196/ 152	Units
DC Forward Current ^[1]	10	mA
Power Dissipation	46	mW
Reverse Voltage (I _R = 100 μA)	5	V
LED Junction Temperature	95	°C
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range	-40 to +85	°C
Soldering Temperature	See reflow soldering profile (Figure 7 & 8)	

Note:

1. Derate linearly as shown in Figure 4.

Electrical Characteristics at T_A = 25°C

Part Number	Forward Voltage V _F (Volts) @ I _F = 10 mA		Reverse Breakdown V _R (Volts) @ I _R = 100 μA	Capacitance C (pF), V _F = 0, f = 1 MHz	Thermal Resistance R _{θJ-PIN} (°C/W)
	Typ.	Max.	Min.	Typ.	Typ.
H SMB-C152/ C172/ C192/ C196	4.0	4.6	5	43	550
H SMB-C112	4.0	4.6	5	43	550

V_F Tolerance: ± 0.1 V

Optical Characteristics at T_A = 25°C

Part Number	Luminous Intensity I _v (mcd) @ 10 mA ^[1]		Peak Wavelength λ _{peak} (nm)	Color Dominant Wavelength λ _d ^[2] (nm)	Viewing Angle 2θ _{1/2} Degrees ^[3]	Luminous Efficacy η _v (lm/w)
	Min.	Typ.	Typ.	Typ.	Typ.	Typ.
H SMB-C112	1.1	3.1	428	462	130	55
H SMB-C172	1.1	3.0	428	462	170	55
H SMB-C192	1.1	3.0	428	462	170	55
H SMB-C196	1.1	3.0	428	462	170	55
H SMB-C152	1.1	3.0	428	462	170	55

Notes:

- The luminous intensity I_v is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the lamp package.
- The dominant wavelength λ_d is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
- θ_{1/2} is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

Blue Color Bin Limits^[1]

Bin ID	Dom. Wavelength (nm)	
	M in.	M ax.
A	460	465
B	465	470
C	470	475
D	475	480

Tolerance: ± 1 nm

Light Intensity (I_v) Bin Limits^[1]

Bin ID	Intensity (mcd)	
	M in.	M ax.
A	0.11	0.18
B	0.18	0.29
C	0.29	0.45
D	0.45	0.72
E	0.72	1.10
F	1.10	1.80
G	1.80	2.80
H	2.80	4.50
J	4.50	7.20
K	7.20	11.20
L	11.20	18.00
M	18.00	28.50
N	28.50	45.00
P	45.00	71.50
Q	71.50	112.50
R	112.50	180.00
S	180.00	285.00
T	285.00	450.00
U	450.00	715.00
V	715.00	1125.00
W	1125.00	1800.00
X	1800.00	2850.00
Y	2850.00	4500.00

Tolerance: $\pm 15\%$

Notes:

- Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Avago representative for information regarding currently available bins.
- The I_v binning specification set-up is for lowest allowable I_v binning only. There are no upper I_v bin limits.

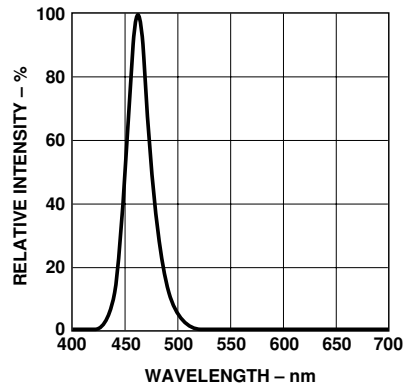


Figure 1. Relative intensity vs. wavelength.

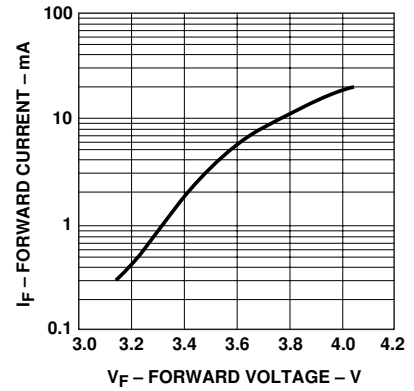


Figure 2. Forward current vs. forward voltage.

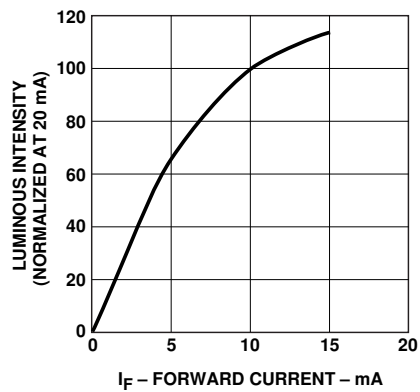


Figure 3. Luminous intensity vs. forward current.

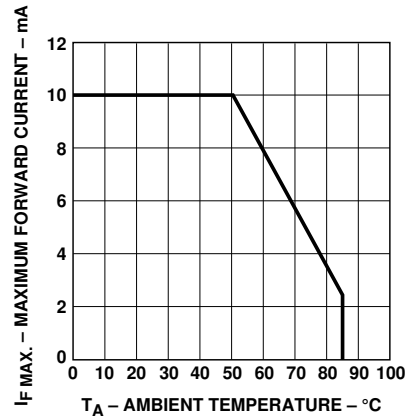


Figure 4. Maximum forward current vs. ambient temperature.

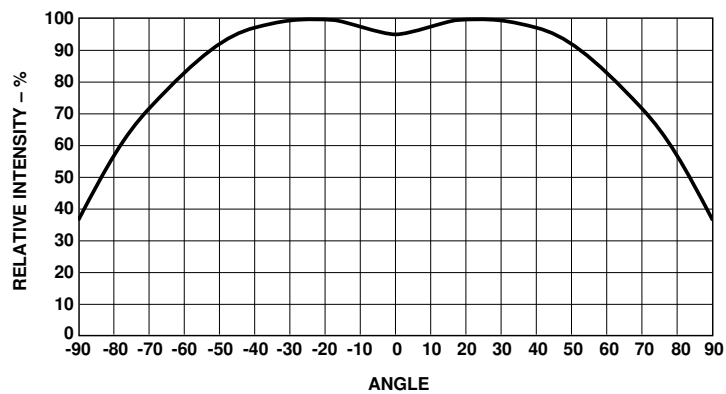


Figure 5. Relative intensity vs. angle for HSM x-C172, C192, C196, and C152.

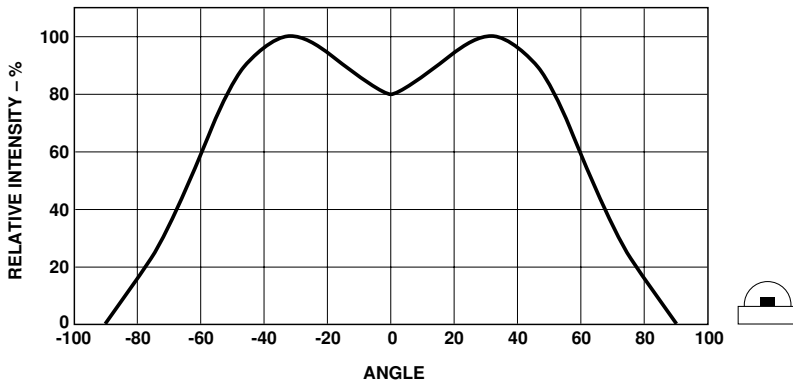


Figure 6. Relative intensity vs. angle for HSM x-C112.

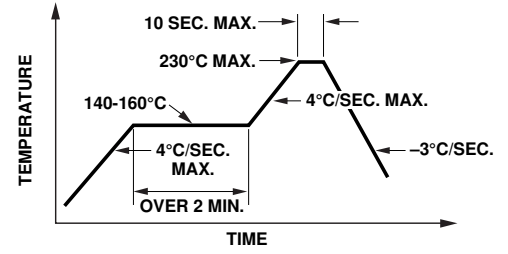
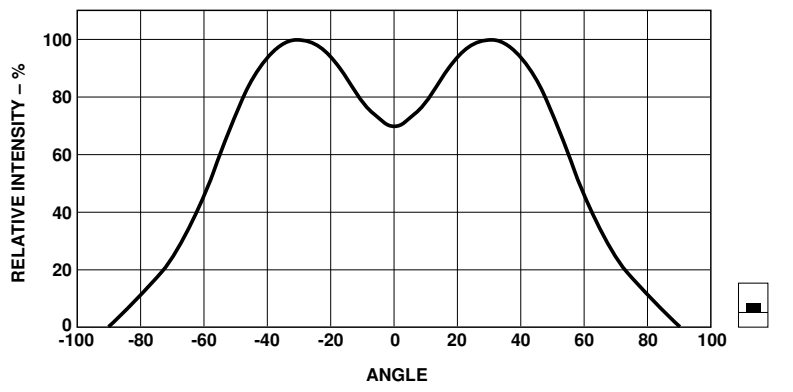


Figure 7. Recommended reflow soldering profile.

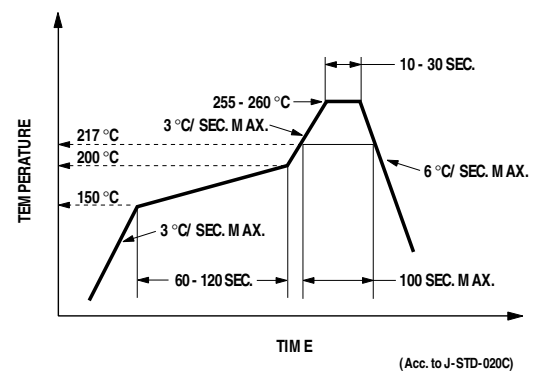


Figure 8. Recommended Pb-free reflow soldering profile.

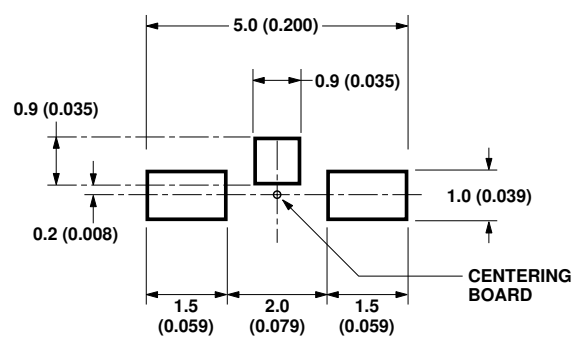


Figure 9. Recommended soldering pattern for HSM x-C112.

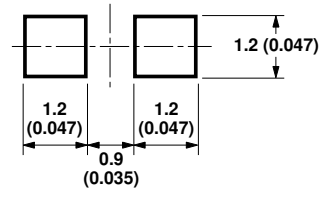


Figure 10. Recommended soldering pattern for HSM x-C172.

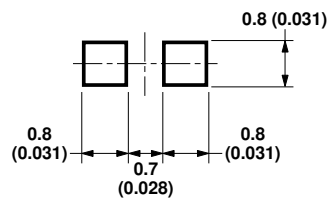


Figure 11. Recommended soldering pattern for HSM x-C192 and HSM x-C196.

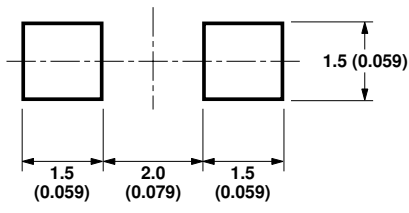


Figure 12. Recommended soldering pattern for HSM x-C152.

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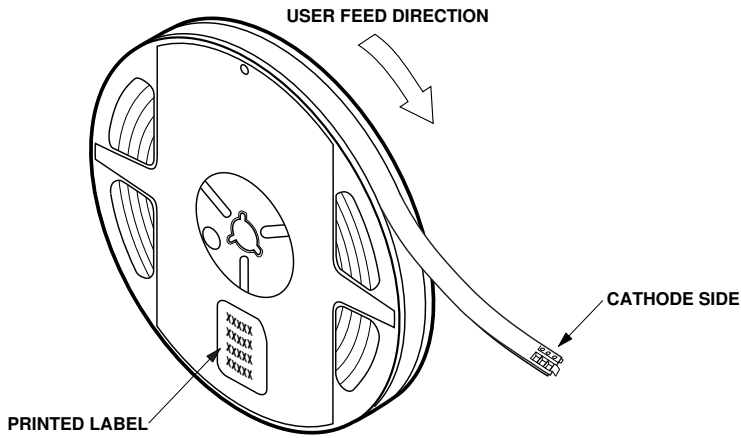
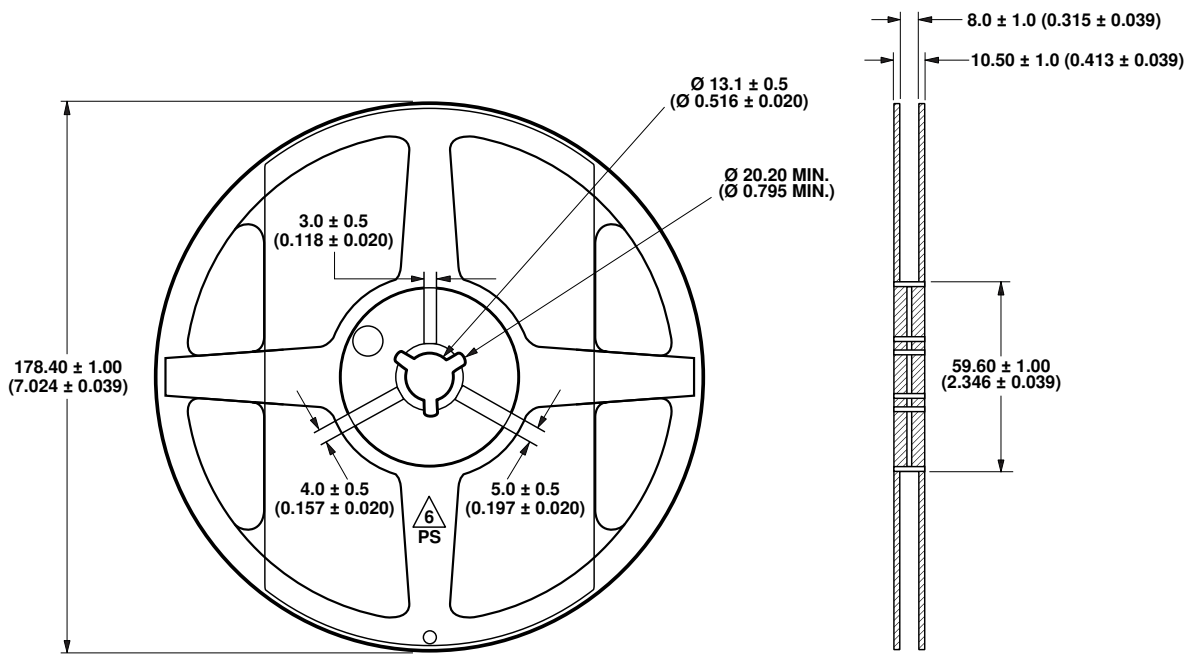


Figure 13. Reeling orientation.



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Figure 14. Reel dimensions.

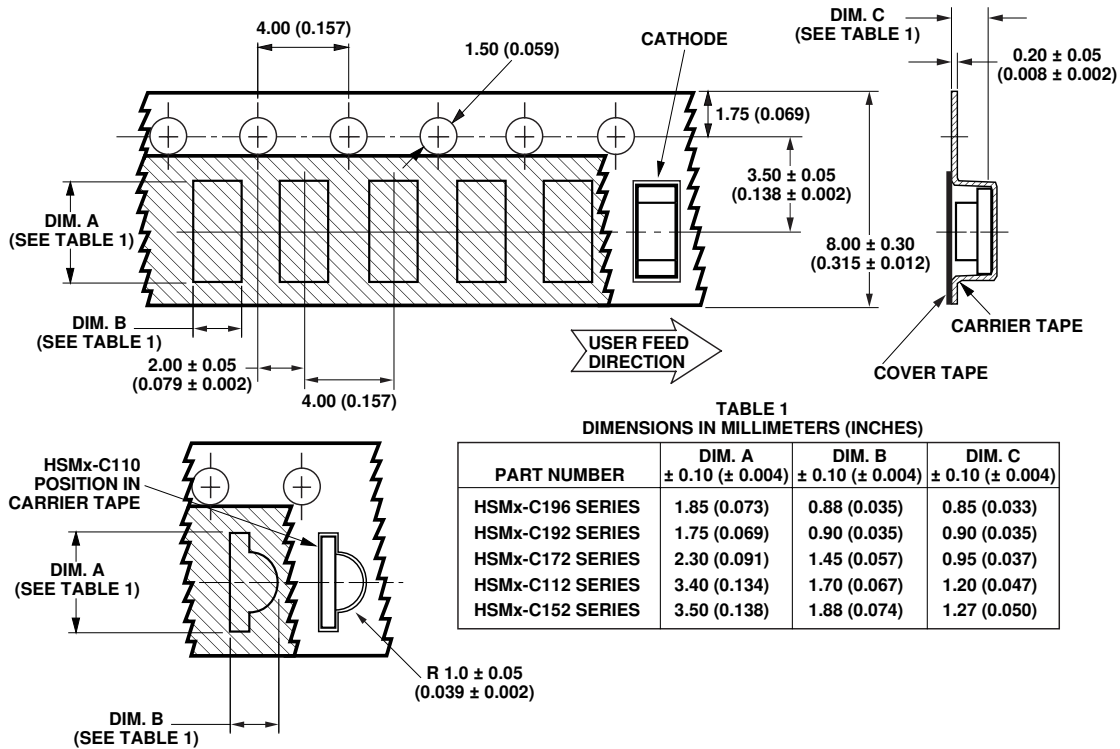


Figure 15. Tape dimensions.

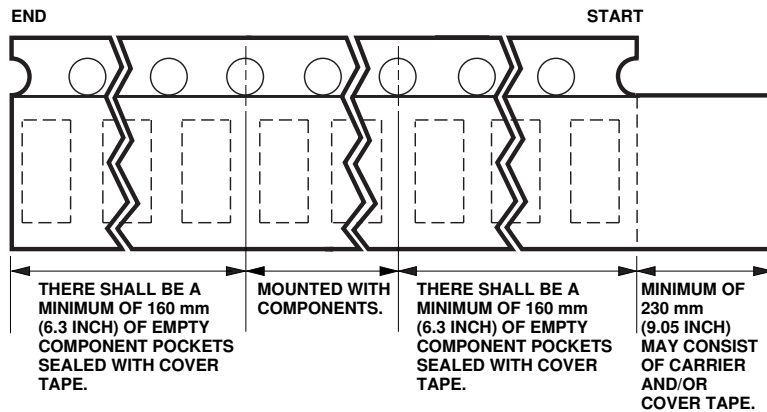


Figure 16. Tape leader and trailer dimensions.

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